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## LAMINATE SUITABLE FOR HIGH FREQUENCY INDUCTION HEATING AND HEAT-SEALING METHOD THEREOF

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### Abstract

**PURPOSE:** To facilitate the controlling of heat sealing conditions and make sure heat sealing possible by a method wherein electrically conducting chip- containing resin layer is provided at the position corresponding to the part necessary for heating on one side of base material and heat sealing layer made of thermoplastic resin is laminated onto the outer surface of said resin layer.

**CONSTITUTION:** In the laminate 1 concerned, electrically conducting chip 3- containing resin layer 4 is provided at the position such as the position corresponding to the mouth 11 of a container 10 on base material 2 consisting of synthetic resin film or thin metal film such as aluminum foil or the like and further heat sealing layer 6 made of thermoplastic resin is provided through adhesive layer 5 on the resin layer 4. when the heat sealing of the mouth 11 of the container 10 by the laminate 1 is intended, heat generates in the electrically conducting chip 3- containing resin layer 4 by placing the laminate 1 below a high frequency induction heating coil 20 under the condition that the laminate 1 is seated onto the mouth 11, resulting in melting the part, which corresponds to the mouth 11 of the container, of the heat sealing layer 6 so as to fusion bond the heat sealing layer 6 to the mouth 11.

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すればよいから加熱条件の制御が容易で、かつ確實なヒートシールを行なうことができるなどの優れた効果がある。

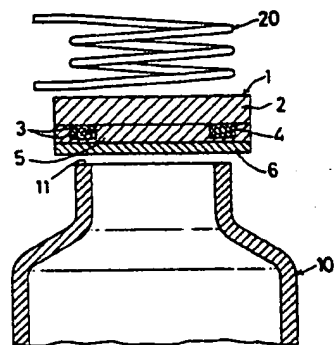
4. 図面の簡単な説明

第1図はこの発明に係る積層体の一実施例を示す断面図、第2図は第2の発明に係る積層体の一実施例を示す断面図である。

- 1、1'……積層体、2……蓋材、  
3……導電性細片、  
4……導電性細片を含む樹脂層、  
4'……導電性細片を含む第2の樹脂層、  
5……接着剤層、6……ヒートシール層、  
7……導電性細片を含む第1の樹脂層、  
10……容器、11……容器の口部、  
20……高周波誘導加熱コイル。

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第1図



第2図

